

C8829D

Conductor

Description

C8829D is a low firing silver conductive paste. It was developed for the Celcion® system and exhibits increased solder leach resistance and improved solderability.

Key Features

- Low firing temperature Increased solder leach resistance Improved solderability Al wire bondable



This picture does not show the packaging of C8829D and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Conductivity	≤ 3.0 milliohms/square at 12 um fired film thickness
Viscosity	150 – 200 Kcps, Brookfield HBTSC4 – 14 spindle and 6R utility cup at 10 rpm, 25 °C
Alloy Ratio	100
Metal	Ag

Recommended Processing Guide

Process Temperature (TDS)	550 – 570 °C peak temperature Dwell time of 5 – 7 minutes
Film Thickness	12 – 20 µm

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